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1. **In the Claims.** The following listing of claims will replace all prior versions of the claims in the application:

1. (Currently Amended) A solder for use in wave-soldering comprising:  
from 88.5% to 93.2% tin;  
from 3.5% to 4.5% silver;  
from 2.0% to 6% indium; and  
from 0.3% to 1% copper; and  
phosphorous present in an amount of not more than 0.01%.
2. (Canceled)
3. (Canceled)
4. (Currently Amended) A solder according to claim 1 which comprises 91.3% tin, 4.2% silver, 4.0% indium, and 0.5% copper and 0.01% phosphorous.
5. (Currently Amended) A solder according to claim 1 which comprises 91.39% tin, 4.1% silver, 4.0% indium, 0.5% copper and 0.0041% phosphorous.
6. (Currently Amended) A method of preparing a solder for use in wave-soldering process, comprising the steps of:
  - (a) mixing tin, silver, indium, and copper and phosphorous to form the solder such that the proportion of tin in the solder is from 88.5% to 93.2%; the proportion of silver in the solder is from 3.5% to 4.5%; the proportion of indium in the solder is from 2.0% to 6%; and the proportion of copper in the solder is from 0.3% to 1.0%, and the proportion of phosphorous in the solder is not more than 0.01%.
7. (Canceled)

8. (Canceled)

9. (Currently Amended) A method according to claim 6 which comprises mixing tin, silver, indium, ~~and copper~~ and phosphorous such that:

the proportion of tin in the solder is 91.3%;

the proportion of silver in the solder is 4.2%;

the proportion of indium in the solder is 4%; ~~and~~

the proportion of copper in the solder is 0.5%; and

the proportion of phosphorous is 0.01%.

10. (Currently Amended) A method according to claim 6 which comprises mixing tin, silver, indium, copper and phosphorous such that:

the proportion of tin in the solder is 91.39%;

the proportion of silver in the solder is 4.1%;

the proportion of indium in the solder is 4%;

the proportion of copper in the solder is 0.5%; and

the proportion of phosphorous in the solder is 0.0041%.

11. (Currently Amended) A method of soldering, comprising the steps of:

(a) forming a solder by combining tin, silver, indium, ~~and copper~~ and phosphorous in the following proportions:

from 88.5% to 93.2% tin;

from 3.5% to 4.5% silver;

from 2.0% to 6.0% indium;

from 0.3% to 1.0% copper; and

phosphorous in an amount not more than 0.01%; and

(b) using the solder formed in step (a) to solder in a wave-soldering process.

12. (Canceled)

13. (Canceled)

14. (Currently Amended) A method according to claim 11 which comprises using a solder comprising 91.3% tin, 4.2% silver, 4.0% indium, and 0.5% copper, and 0.01% phosphorous.

15. (Currently Amended) A method according to claim 11 which comprises using a solder comprising 91.39% tin, 4.1% silver, 4.0% indium, 0.5% copper and 0.0041% phosphorous.

16. (Canceled)

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